ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSSOP 14-28 LEAD					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
BOND INT	160	80,000	200°C + N2	0	0.00
HAST	2,050	202,500	130°C, 85%RH	0	0.00
Pressure Pot	5,607	547,872	121°, 15 PSIG	0	0.00
Solder DUNK	590	1,830	260°C, 10SEC	0	0.00
Solderability	840	6,960	883 M2003	0	0.00
Temp Cycle	6,260	2,183,000	−65°C−150°C	0	0.00
Thermal Shock	850	8,500	−60°C−150°C	0	0.00